

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/04/2022

Details for "OPA2300AIDGSRG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA2300AIDGSRG4	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DGS 10	3x3x1	33

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.039854	99.984947	999849	0.120879	1209
Not Categorized	Proprietary Materials		0.000005	0.012544	125	0.000015	0
Precious Metals	Silver	7440-22-4	0.000001	0.002509	25	0.000003	0
Sub-Total			0.03986	100	1000000	0.120897	1209
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.240937	81.999891	819999	0.73077	7308
Thermoplastics	Epoxy	85954-11-6	0.052889	18.000109	180001	0.160414	1604
Sub-Total			0.293826	100	1000000	0.891184	8912
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	16.266549	94.649994	946500	49.337004	493370
Magnesium and Its Alloys	Magnesium	7439-95-4	0.030076	0.175003	1750	0.091222	912
Nickel and Its Alloys	Nickel	7440-02-0	0.549952	3.2	32000	1.668023	16680
Other Inorganic Materials	Silicon	7440-21-3	0.124599	0.725003	7250	0.377913	3779
Precious Metals	Silver	7440-22-4	0.214825	1.25	12500	0.651572	6516
Sub-Total			17.186001	100	1000000	52.125734	521257
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.237412	97.3	973000	0.720079	7201
Precious Metals	Gold	7440-57-5	0.000732	0.3	3000	0.00222	22
Precious Metals	Palladium	7440-05-3	0.005124	2.1	21000	0.015541	155
Precious Metals	Silver	7440-22-4	0.000732	0.3	3000	0.00222	22
Sub-Total			0.244	100	1000000	0.74006	7401
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	13.454124	93.500003	935000	40.806822	408068
Other Plastics and Rubber	Carbon Black	1333-86-4	0.071947	0.499999	5000	0.218218	2182
Thermoplastics	Epoxy	85954-11-6	0.863366	5.999998	60000	2.618619	26186
Sub-Total			14.389437	100	1000000	43.643659	436437
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.817157	100	1000000	2.478465	24785
Sub-Total			0.817157	100	1000000	2.478465	24785
Total			32.970281			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.